resin (A) and the phenoxy resin (C) is from 10 to 60% by mass, preferably from 15 to 50% by mass, and more preferably from 18 to 45% by mass.

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(Inorganic filler (D))

The inorganic filler (D) used may be an inorganic filler usually used in a transparent adhesive composition as long as the effects of the present invention are not impaired.

Examples of the inorganic filler (D) include each inorganic powder made of ceramics (e.g., silica, clay, gypsum, calcium carbonate, barium sulfate, alumina (aluminum oxide), beryllium oxide, magnesium oxide, silicon carbide, silicon nitride, aluminum nitride, boron nitride), a metal or alloys (e.g., aluminum, copper, silver, gold, nickel, chromium, lead, tin, zinc, palladium, solder), and carbons (e.g., carbon nanotube, graphene).

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The inorganic filler (D) is preferably a silica filler (D1) from the viewpoint of enhancing the melt viscosity and the reliability (specifically, imparting, for instance, a low linear expansion coefficient, a low water absorption rate).

From the viewpoint of storage stability and transparency, the average particle diameter (d50) of the silica filler (D1) is preferably from 0.01 to 1.0 μm, preferably from 0.01 to 0.8 μm, preferably from 0.01 to 0.3 μm, and more preferably from 0.01 to 0.2 μm.

From the viewpoint of storage stability and transparency, the particle diameter (d90) of the silica filler (D1) at 90% cumulative distribution frequency is preferably from 0.05 to 2.0 μm, preferably from 0.05 to 1.0 μm, and more preferably from 0.1 to 1.0 μm. The particle diameter (d90) of the silica filler (D1) at 90% cumulative distribution frequency is also preferably 1.0 μm or less.

From the viewpoint of storage stability and transparency, the silica filler (D1) more preferably satisfies the following (3) and (4).